



20V N-Channel MOSFETs

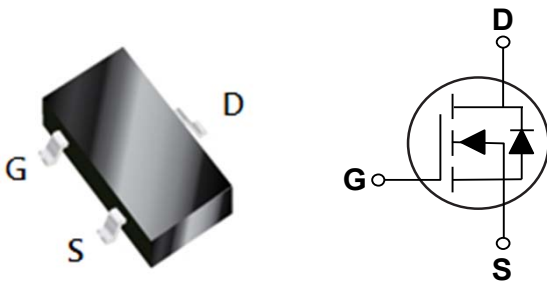
General Description

The TLMNB060 is the high cell density trench N-ch MOSFETs, which provides excellent $R_{DS(ON)}$ and efficiency for most of the small power switching and load switch applications.

The TLMNB060 meets the RoHS and Green Product requirement with full function reliability approved.

BV_{DSS}	R_{DS(ON)}	I_D
20 V	60 mΩ	3.6 A

SOT-23S Pin Configuration



Features

- 20V, 3.6A, $R_{DS(ON)} \leq 60m\Omega @ V_{GS}=4.5V$
- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Advanced high cell density Trench technology

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current - Continuous, $V_{GS} @ 4.5V$ (NOTE 1) ($T_A=25^\circ C$)	3.6	A
	Drain Current - Continuous, $V_{GS} @ 4.5V$ (NOTE 1) ($T_A=70^\circ C$)	2.8	A
I_{DM}	Drain Current - Pulsed (NOTE 2)	14.4	A
P_D	Total Power Dissipation (NOTE 3) ($T_A=25^\circ C$)	1	W
T_J	Operating Junction Temperature Range	-50 to 150	$^\circ C$
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ C$
Marking Code		2302	

Thermal Characteristics

Symbol	Parameter	Typ.	Max	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (NOTE 1)	---	125	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case (NOTE 1)	---	80	$^\circ C/W$



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	20	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =16V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =16V, V _{GS} =0V, T _J =55°C	---	---	5	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±12V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance (NOTE 2)	V _{GS} =4.5V, I _D =3A	---	---	60	mΩ
		V _{GS} =2.5V, I _D =2A	---	---	86	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	0.4	---	1.2	V
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =3A	---	10.5	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _D =3A	---	4.6	---	nC
Q _{gs}	Gate-Source Charge		---	0.7	---	
Q _{gd}	Gate-Drain Charge		---	1.5	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =10V, V _{GS} =4.5V, R _G =3.3Ω, I _D =3A	---	1.6	---	ns
T _r	Rise Time		---	42	---	
T _{d(off)}	Turn-Off Delay Time		---	14	---	
T _f	Fall Time		---	7	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1MHz	---	310	---	pF
C _{oss}	Output Capacitance		---	49	---	
C _{riss}	Reverse Transfer Capacitance		---	35	---	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current (NOTE 1 · 4)	V _G =V _D =0V, Force Current	---	---	3.6	A
V _{SD}	Diode Forward Voltage (NOTE 2)	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.2	V

NOTES :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. The power dissipation is limited by 150°C junction temperature.
4. The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.



Characteristics Curves

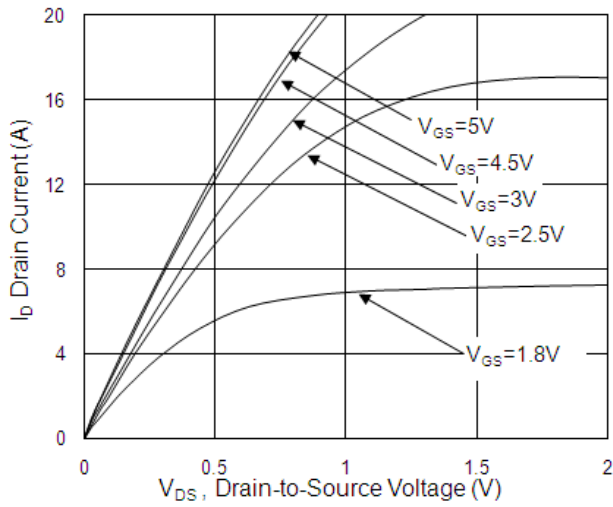


Fig.1 Typical Output Characteristics

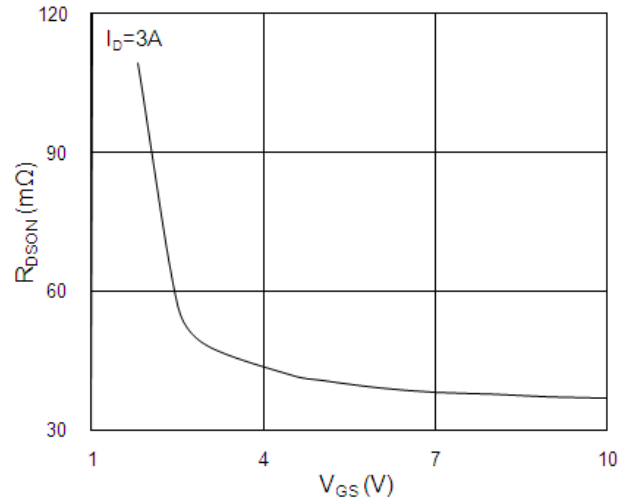


Fig.2 On-Resistance vs. G-S Voltage

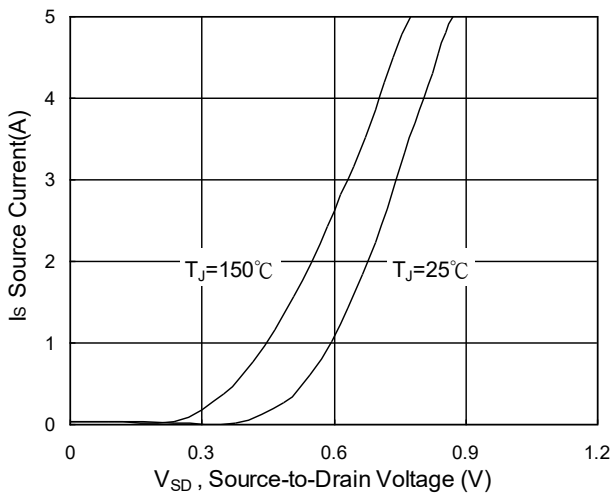


Fig.3 Source Drain Forward Characteristics

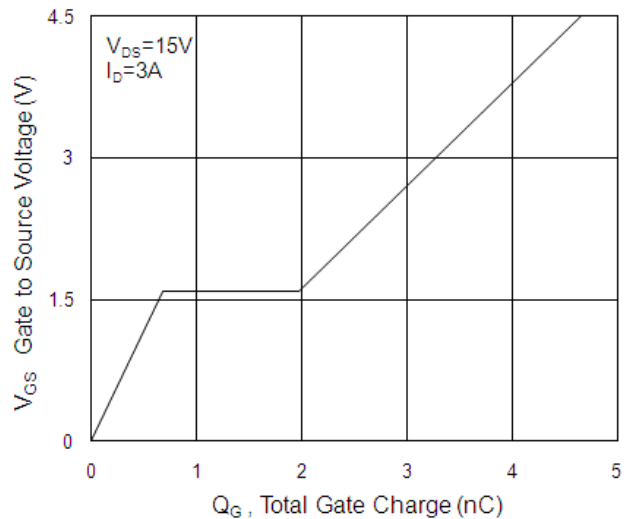


Fig.4 Gate-Charge Characteristics

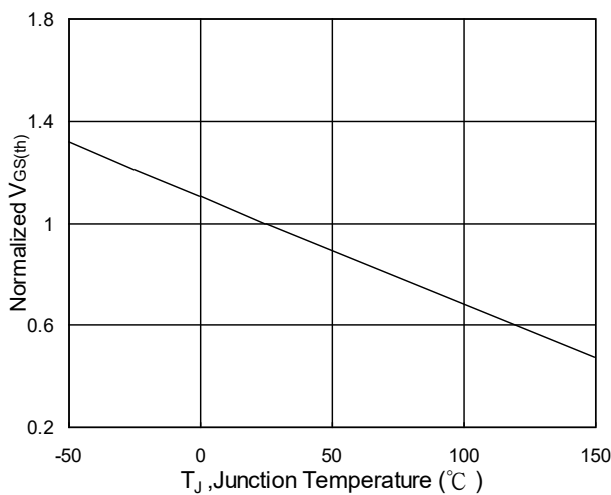


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

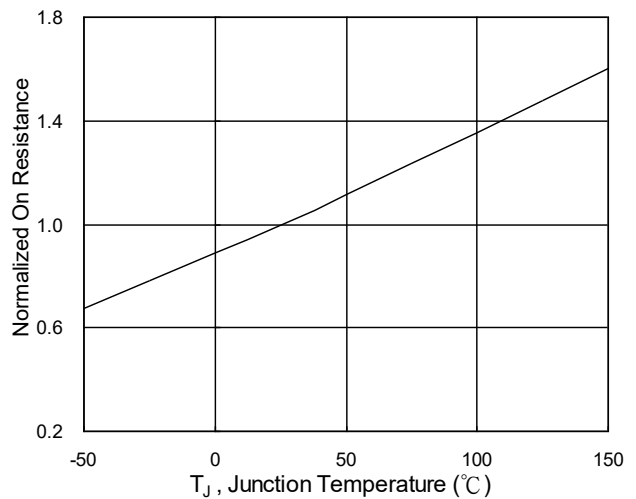


Fig.6 Normalized $R_{DS(on)}$ vs. T_J



Characteristics Curves

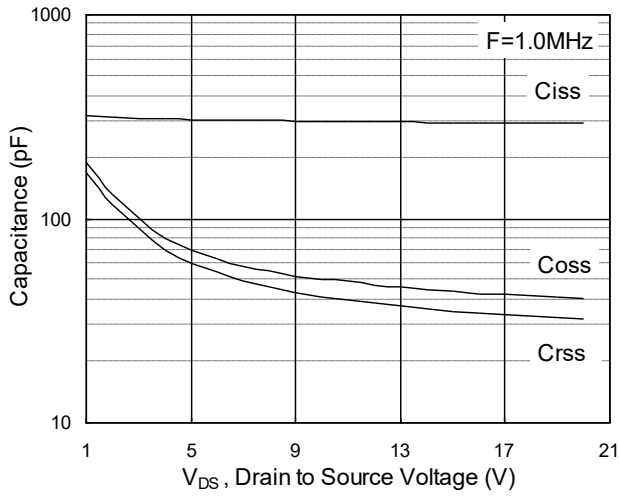


Fig.7 Capacitance

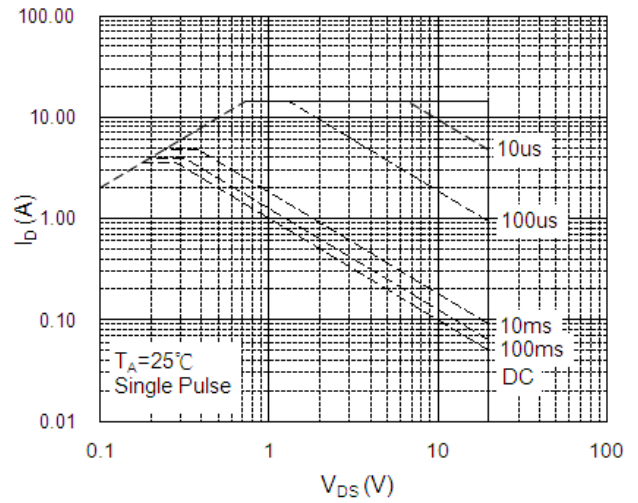


Fig.8 Safe Operating Area

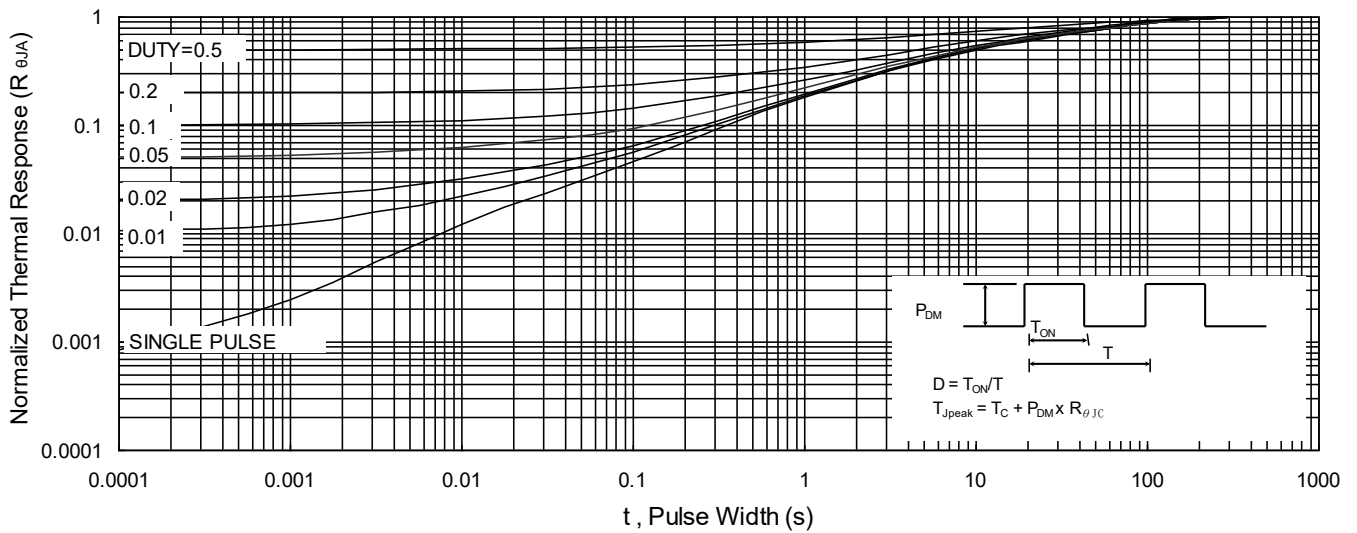


Fig.9 Normalized Maximum Transient Thermal Impedance

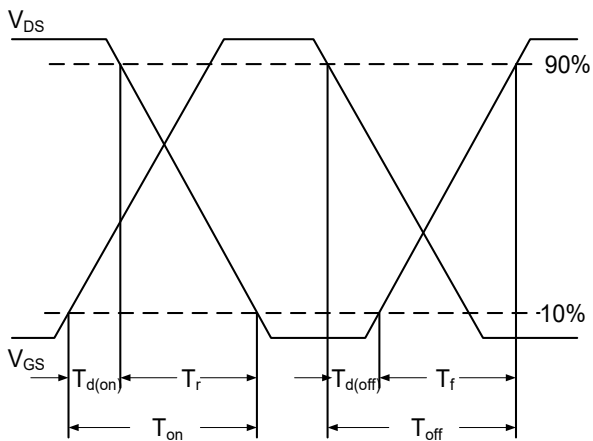


Fig.10 Switching Time Waveform

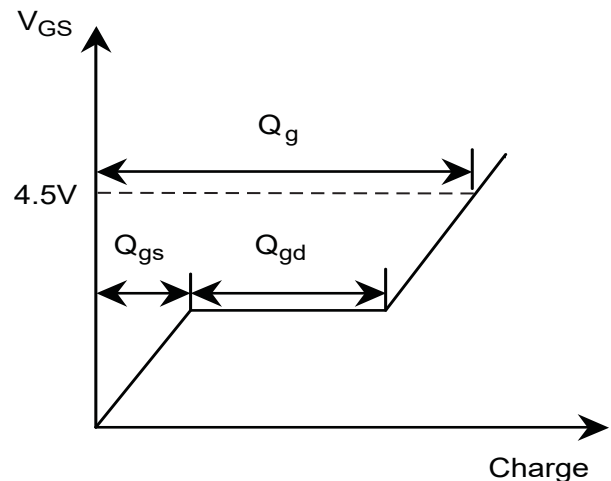
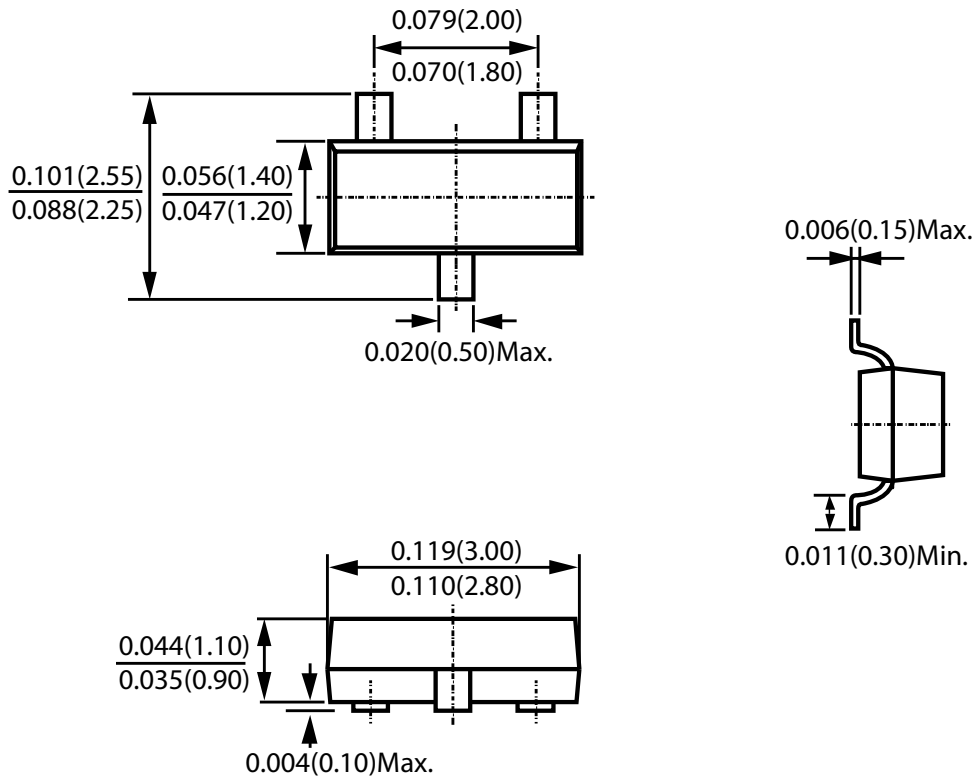


Fig.11 Gate Charge Waveform



Package Outline Dimensions



SOT-23S

Dimensions in inches and (millimeters)



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